



ESD SMD Comm COG, Ceramic, 6,800 pF, 1%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

6,800 pF

1 kHz 1.0Vrms

0% Loss/Decade Hour

100 GOhms

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

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1.6mm +/-0.35mm	Tolerance	1%
0.78mm +/-0.20mm	Voltage DC	25 VDC
1.5mm MIN	ESD Level per AEC-Q200	25,000 V ESD Level
0.6mm +/-0.25mm	Dielectric Withstanding Voltage	62.5 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
Bulk, Bag	Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
1	Reference to +25°C and 0 VDC Applied (TCC)	
	Dissipation Factor	0.1% 1 kHz 1.0Vrms

Specifications
Capacitance

Aging Rate

Insulation Resistance

Measurement Condition

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

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